

Aprep Fine polishing suspensions

QPREP fine polishing suspensions are the polishing products of choice for the most demanding polishing requirements. This involves chemical mechanical polishing using silicon dioxide or aluminum oxide.



PRODUCT ADVANTAGES

- I Highest surface qualities
- I Removal of all deformation with vibration polishing
- Polishing/removing scratches in the range of 0.1µm to 0.05µm

RECOMMENDED APPLICATIONS

- I Detailed microstructure analysis
- Very soft or very hard and ductile materials

Item No.	Unit	Description			
		FINE POLISHING SUSPENSIONS			
		Description	ph-value	Grain Size	
		Fine polishing s does not crys for ferrous mannerals	tallize	2 3-	osites, PCB, rocks and
92002534	11	Eposal	pH≈8.0	0.06 µm	
		Colloidal silica • for polishing, also mixable with diluted etchant • for ferrous and non-ferrous materials, ceramics • especially for soft materials like Al,Cu,Ti and solder joints			
92002536	1	Eposil F	pH≈9.5	0.1 µm	
95013858	11	Eposil Non Dry	pH≈9.5	0.05 µm	(does not crystallize)
95013958	10 I	Eposil Non Dry	pH≈9.5	0.05 µm	(does not crystallize)
92002541	1 kg	Eposil M	pH≈9.5	0.06 µm	
		Colloidal silica • for titanium, nickel, tin and its alloys			
95001206	1 kg	Eposil M11	pH≈11.0	0.06 µm	
		Water-free fine polishing suspension • e.g. for magnesium, zinc			
95005033	1 kg	Etosil E	pH≈7.0	0.06 µm	
		ALUMINA SU	JSPENSIO1	N, CALCINA	ATED
		Description		Grain Size	
		Aqueous concentrate, to dilute, 3-5 part of dest. water			
92002533	11	Alumina suspension		0.3 µm	
92002532	11	Alumina susper	Alumina suspension		
92004950	11	Alumina susper	Alumina suspension		